



# Analog Devices Welcomes Hittite Microwave Corporation

NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED









#### Typical Applications

The HMC305BLP4E is ideal for:

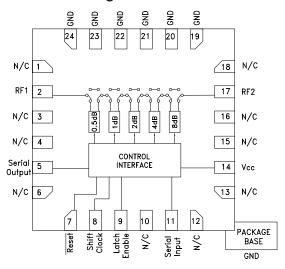
- Cellular/3G Infrastructure
- Fixed Wireless, WiMax & WiBro
- Test Instrumentation

#### **Features**

0.5 dB LSB Steps to 15.5 dBCMOS Compatible Serial Data InterfaceSPI Compatible Serial Output±0.3 dB Typical Bit Error

24 Lead 4x4mm QFN Package: 16mm²

#### **Functional Diagram**



#### **General Description**

The HMC305BLP4E is a broadband 5-bit positive control GaAs IC digital attenuator with CMOS compatible serial-to-parallel driver package in a leadless QFN 4x4 mm SMT package. Covering 0.7 to 3.8 GHz, the insertion loss is typically less than 1.5 to 2 dB. The attenuator bit values are 0.5 (LSB), 1, 2, 4, and 8 dB for a total attenuation of 15.5 dB. Attenuation accuracy is excellent at  $\pm$ 0.25 dB typical with an IIP3 of up to +52 dBm. Five bit serial control words are used to select each attenuation state. A single Vcc bias of +3V to +5V applied through an external 5 kOhm resistor is required.

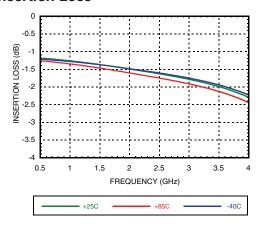
#### Electrical Specifications, $T_A = +25^{\circ}$ C, Vcc = +3V to +5V

Parameter		Frequency	Min.	Typical	Max.	Units
Insertion Loss		0.7 - 1.4 GHz 1.4 - 2.3 GHz 2.3 - 2.7 GHz 2.7 - 3.8 GHz		1.2 1.5 1.8 2.0	1.5 2.0 2.3 2.5	dB dB dB dB
Attenuation Range		0.7 - 3.8 GHz		15.5		dB
Return Loss (RF1 & RF2, All Atten. States)		0.7 - 1.4 GHz 1.4 - 2.3 GHz 2.3 - 2.7 GHz 2.7 - 3.8 GHz		20 21 23 21		dB dB dB dB
Attenuation Accuracy: (Referenced to Insertion Loss) All Attenuation States		0.7 - 0.9 GHz 0.9 - 2.2 GHz 2.2 - 3.8 GHz	± (0.3 +4	% of Atten. Set % of Atten. Set % of Atten. Set	ting) Max	dB dB dB
Input Power for 0.1 dB Compression	Vcc = 5V Vcc = 3V	0.7 - 3.8 GHz		26 25		dBm dBm
Input Third Order Intercept Point (Two-tone Input Power = 10 dBm Each Tone)	Vcc = 5V Vcc = 3V	0.7 - 3.8 GHz		52 48		dBm dBm
Switching Characteristics tRISE, tFALL (10/90% RF) tON, tOFF (Latch Enable to 10/90% RF)		0.7 - 3.8 GHz		750 830		ns ns



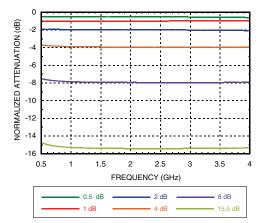


#### **Insertion Loss**



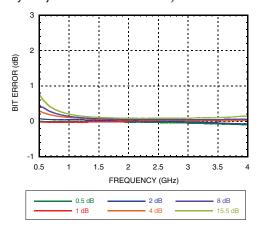
#### **Normalized Attenuation**

(Only Major States are Shown)



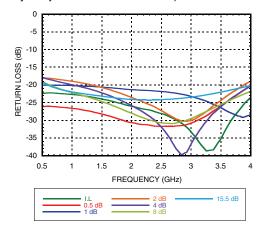
#### Bit Error vs. Frequency

(Only Major States are Shown)

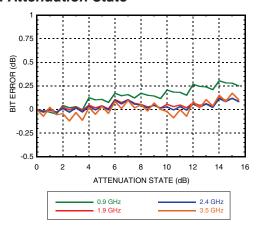


#### Return Loss RF1, RF2

(Only Major States are Shown)

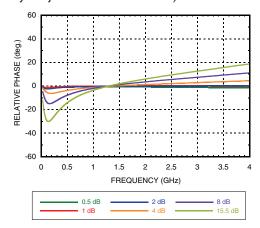


### Bit Error vs. Attenuation State



#### Relative Phase vs. Frequency

(Only Major States are Shown)

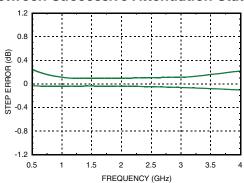


Note: All Data Typical Over Voltage (+3V to +5V) & Temperature (-40°C to +85°C).





#### Worst Case Step Error Between Successive Attenuation States



#### **Digital Control Voltages**

State	Vcc = +5V	Vcc = +3V
Low	0 to 1.3V	0 to 0.7V
High	3.5 to 5V	2.3 to 3V

#### Serial Input Truth Table

Latch Enable	Shift Clock	Reset	Function
Х	Х	L	Shift register cleared
Х	<b>1</b>	Н	Shift register clocked
<b>↑</b>	x	Н	Contents of shift register transferred to Digital Attenuator

#### **Timing**

Parameter	Symbol	Vcc = +5V		Vcc = +3V		Units
r dramotor		Min.	Max.	Min.	Max.	
Serial Input Setup Time	ts	20	ı	100	-	ns
Hold time from Serial Input to Shift Clock	th	0	ı	5	-	ns
Setup time from Shift Clock to Latch Enable	tlsup	40	-	100	-	ns
Propagation delay, Latch Enable to C0.5 through C8	tpd	-	30	-	70	ns
Setup time from Reset to Shift Clock	-	20	-	50	-	ns
Clock Frequency (1/tclk)	fclk	-	30	-	10	MHz

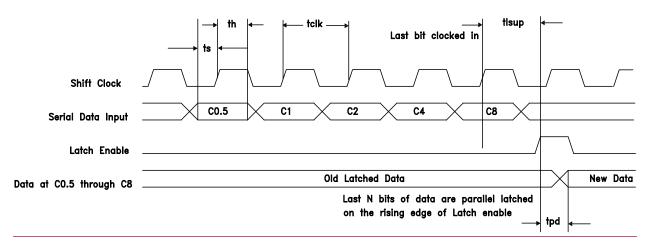
#### **Truth Table**

Serial Control Input					Attenuation	
C 0.5	C 1	C 2	C 4	C 8	Setting RF1 - RF2	
High	High	High	High	High	Reference I.L.	
Low	High	High	High	High	0.5 dB	
High	Low	High	High	High	1 dB	
High	High	Low	High	High	2 dB	
High	High	High	Low	High	4 dB	
High	High	High	High	Low	8 dB	
Low	Low	Low	Low	Low	15.5 dB Max. Atten.	
Any cor	Any combination of the above states will provide an attenuation					

Any combination of the above states will provide an attenuation approximately equal to the sum of the bits selected.

#### **Timing Diagram**

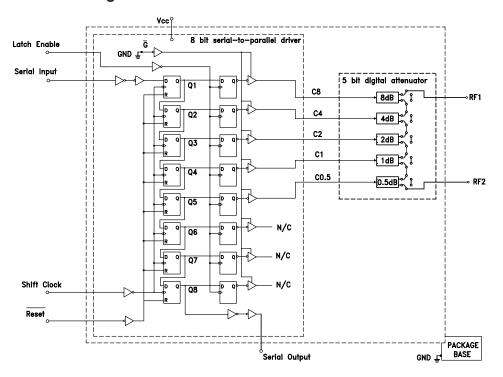
Serial data is shifted in on the rising edge of the Shift Clock, LSB first, and is latched on the rising edge of Latch Enable.



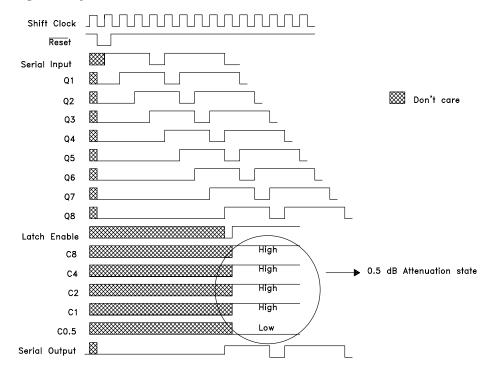




#### Logic / Functional Diagram



#### Programming Example to Select 0.5 dB Attenuation State







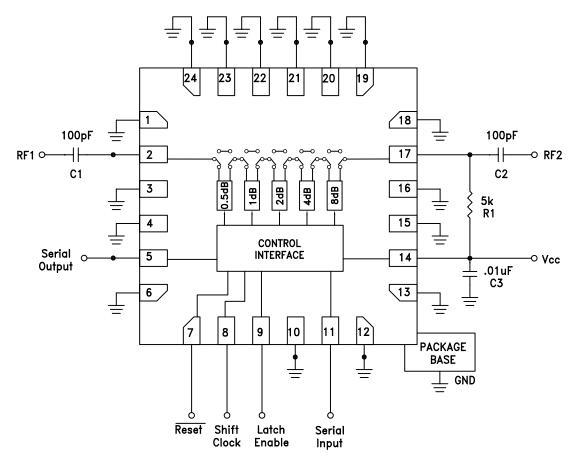
#### **Pin Descriptions**

Pin Number	Function	Description	Interface Schematic
1, 3, 4, 6, 10, 12, 13, 15, 16, 18	N/C	These pins are not connected internally. However, all data shown herein was measured with these pins connected to RF/DC Ground.	
2, 17	RF1, RF2	This pin is DC coupled and matched to 50 Ohms Blocking capacitors are required. Select value based on lowest frequency of operation.	RF1, 0 0 0
5	Serial Output	Serial data output. Serial input data delayed by 8 clock cycles	Vcc O Serial Output
7	Reset	See truth table, control voltage table and timing diagram.	20Kn > 300n Reset 0
8	Shift Clock		V <sub>cc</sub>
9	Latch Enable		Shift Clock 3000 Latch Enable 0
11	Serial Input		
14	Vcc	Supply Voltage.	
19 - 24	GND	Package bottom has an exposed metal paddle that must also be connected to RF/DC Ground.	→ GND =





#### **Application Circuit**



DC blocking capacitors C1 & C2 are required on RF1 & RF2. Choose C1 = C2 =  $100 \sim 300$  pF to allow lowest customer specific frequency to pass with minimal loss. R1 = 5 kOhm is required to supply voltage to the circuit through either PIN 2 or PIN 17.



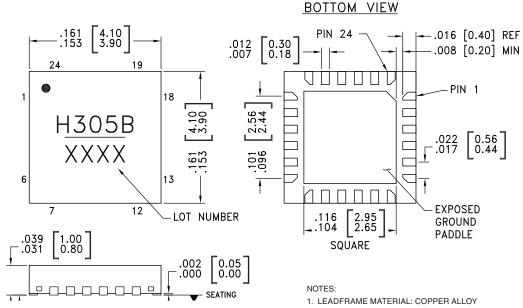


#### **Absolute Maximum Ratings**

Digital Inputs (Reset, Shift Clock, Latch Enable & Serial Input)	-0.5 to (Vcc + 0.5) V
Digital Outputs (Serial Output)	-0.5 to (Vcc + 0.5) V
DC Current on Serial Output	±35 mA
Bias Voltage (Vcc)	+5.6 V
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
RF Input Power (0.7 - 3.8 GHz)	+26 dBm
ESD Sensitivity (HBM)	Class 1A



#### **Outline Drawing**



- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
   PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

#### **Package Information**

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [2]
HMC305BLP4E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [1]	H305B XXXX

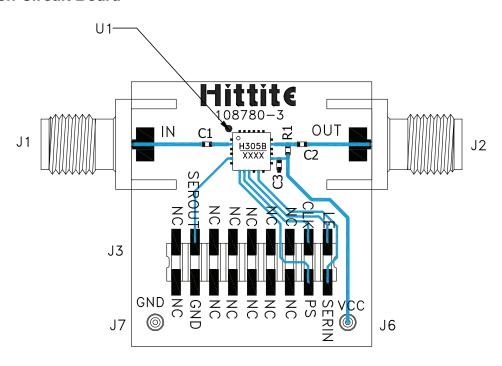
<sup>[1]</sup> Max peak reflow temperature of 260 °C

<sup>[2] 4-</sup>Digit lot number XXXX





#### **Evaluation Circuit Board**



#### List of Materials for Evaluation PCB EVAL01 - HMC305BLP4 [1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3	18 Pin DC Connector
J6, J7	DC Pin
C1, C2	100 pF Capacitor, 0402 Pkg.
C3	0.01 μF Capacitor, 0402 Pkg.
R1	5 kOhm Resistor, 0402 Pkg.
U1	HMC305BLP4E Digital Attenuator
PCB [2]	108780 Evaluation PCB

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed ground paddle should be connected directly to the ground plane similar to that shown below. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board as shown is available from Hittite Microwave Corporation upon request.

<sup>[2]</sup> Circuit Board Material: Rogers 4350